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SSP INC

REALIZING TECHNOLOGY FOR MAKING IMAGINATION INTO REALITY

Micro Solder Ball Mounting
Dispensing & Curing
Package Sorter
Flux Printing
Tape Attach & Detach
Camera Module Assembly
Solder Paste Dotting
Copper Post Mounting
Weight Bar Handling System with Brush Cleaning
Plasma Cleaning
SMT Module Automation System



ABOUT US

COMPANY INTRODUCTION

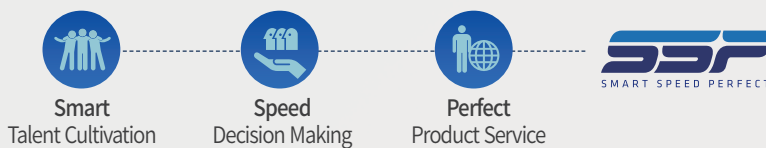
"REALIZING TECHNOLOGY FOR MAKING IMAGINATION INTO REALITY"

Greetings, I would like to extend warm welcome and gratitude for visiting SSP, a semiconductor equipment manufacturer, growing to be the global leader in the field.

Since our establishment in 1996, we have been growing together with customers as a company specialized in manufacturing of semiconductor equipment through active investment on talent fostering and technology innovation based on our management philosophy
"Realizing Technology for Making Imagination into Reality"

We foster technical experts with expertise and creativity. Acknowledged for our innovative design and technological innovation, we aim to become the global leader in the field.

Furthermore, we consider creating value for our customers as our highest priority and we are dedicated to providing the value customers need. Please support SSP on accomplishing the vision of "2030 Global Technology Leading Company" by strengthening the core competences, advancing management system and operating organization efficiently through technical innovation and challenges.



Sincerely yours.
CEO

TECHNOLOGY / CERTIFICATE



BRIEF HISTORY

SSP's History Accomplished by Continuous Technology Development

Ball Placement System

Lid Attach & Cure System

Package Sorter System

SMT Module Automation System

Camera Module System

2021 ~ Present

Accelerating business growth

Achieved 30 Million US\$ Export (2022)
Developed Dispensing & Lid Attach System (DAP)
Developed Laser Lid Attach System (DAL)
Developed Solder Paste Multidotting System (MPD)
Developed Copper Post Mounting System (CPM)
Registered 17 Patents (Laser Cure & Tooling)
Move New Factory (Incheon Techno Park)

2011 ~ 2015

Shared future together

Established New Factory & HQ (2011)
Developed New Ball Mount System (BPS8200,7200FC)
Developed Multi Pickers Package Sorter System for EMI Shield
Developed Wafer Level Micro Ball Mount System
Selected as Hope-to-be-Hired Company
Registered 20 patents

2001 ~ 2005

Concentrated on technology and quality

Developed Holder Attach System (Camera Module)
Developed Auto Solder Ball Mount System (FC BGA)
Developed Auto Screen Printing System (FC BGA)
ISO 9000 Certification (2004)
Registered R&D Center (KITA - 2004)
Attained INNO - BIZ Company (SMBA - 2004)
3 Million US\$ Export Prize (KOTRA - 2005)
Registered 6 Patents (Ball Mounting & Camera Module)
Move New Factory (Incheon Namdong Industrial Zone)



HISTORY

SSP's History Accomplished by Continuous Technology Development

2016 ~ 2020

Growing into a global construction leader

Developed New Ball Mount System with Automation
Developed Ball Placement System Dual Head
Developed Filter Inspection System for Camera Module
ISO 45001 Certification
Selected as Global Small Giant Company
Presidential Citation in venture promotion
The best badge in honor the Red Cross
Registered 40 Patents

2006 ~ 2010

Continued strategy of technological advancement

Developed New Ball Mount M/C (BPS 7200)
Developed Active Align System (8 M Camera Module)
Developed FCBGA Automation Line
CE Certification for Auto Holder Attach System
5 Million US\$ Export Prize (KOTRA - 2007)
10 Million US\$ Export Prize (KOTRA - 2010)
ISO 14000 Certification (2010)
Selected as Export Blue chip Company (Incheon City)
Registered 18 Patents

1996 ~ 2000

Foundation and Progress

Founded Seoul Semiconductor Precision (1996-06)
Developed Auto Solder Ball Mount System (PBGA/CA)
CE Certification for Ball Mount System
Developed Auto Lamination System
Developed Semi Auto IC Cutting Equipment (FlexBGA)
Attained Venture Company
Registered 5 Patents for Solder Ball Mounting Tech

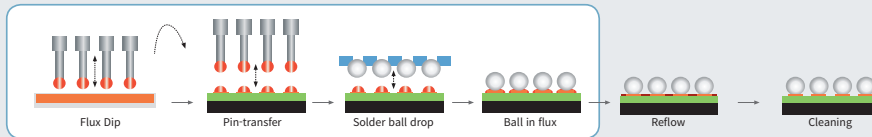
PRODUCT LINEUP 1

Micro Solder Ball Mounting

BPS-8200 BPS-8200FC BPS-8200S

• **Application** : FCBGA, BGA, FCCSP

• **Process**

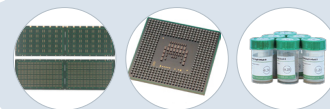


Carrier : Magazine, Boat



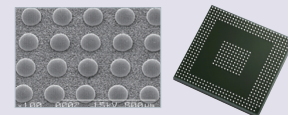
INPUT

Material : Strip, Singulated Unit, Solder Ball



Interface Type : Downstream Link, Standalone

OUTPUT

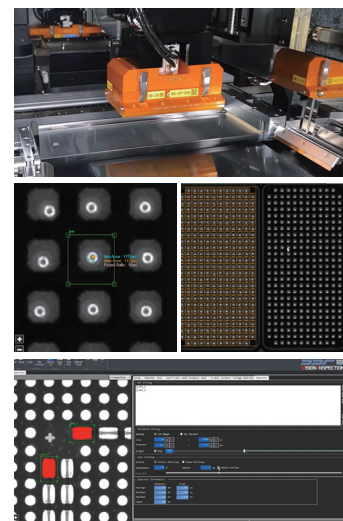


• **System Performance**

Cycle Time	Strip, Single Boat, Matrix Boat
Yield Performance	99.98 %
Placement Accuracy	± 0.02mm
Fine Pitch Capability	0.20 mm (for Ø0.10 mm)
Strip Handling Capacity	50-95 mm Width × 180-260 mm Length
Product Flexibility	All kinds of laminated Substrate BGA Package series
Quick Conversion Time	Ball tool, Flux tool, Lift Block
Foot Print & Weight	2,300(L) × 1,350(W) × 1,820(H)
Foot Weight	3,000 kg

• **Optional Features**

- Thin PCB Thickness : 70 μm
- Pad Edge to Component Distance : Min. 100 μm
- Auto Ball Supply
- Cleanliness : Class 1,000
- Certification : CE, UL508A, SEMI S2, etc.



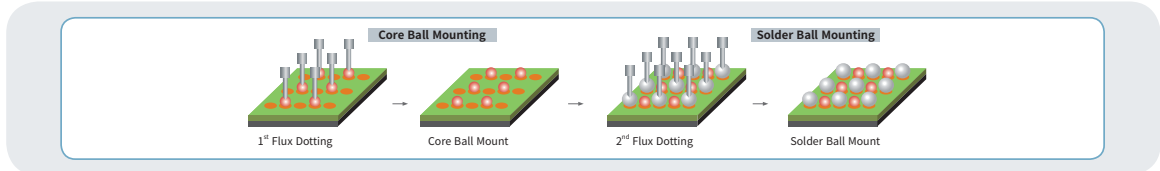
PRODUCT LINEUP 2

Dual Ball Placement System

BPS-DH2

• **Application** : FCBGA, BGA, FCCSP

• **Process**



Carrier : Magazine, Boat

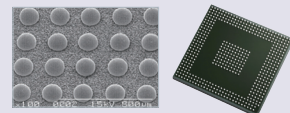


Material : Strip, Singulated Unit, Solder Ball



Interface Type : Downstream Link, Standalone

OUTPUT

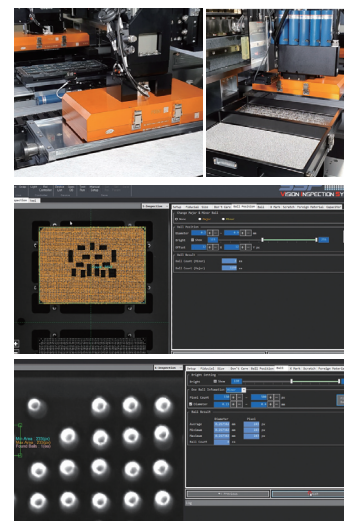


• **System Performance**

Cycle Time	Single Ball 16 sec Dual Ball 25-28 sec
Yield Performance	99.98 %
Placement Accuracy	± 0.02mm
Fine Pitch Capability	0.4 mm (for Ø0.15 mm)
Strip Handling Capacity	75-210 mm Width × 250-320 mm Length
Product Flexibility	Singulated Unit BGA
Quick Conversion Time	Ball tool, Flux tool, Lift Block
Foot Print & Weight	3,100(L) × 2,380(W) × 1,870(H)
Foot Weight	5,000 kg

• **Optional Features**

- Dual Ball Inspection
- Pad Edge to Component Distance : Min. 100 µm
- Auto Ball Supply
- Cleanliness : Class 1,000
- Certification : CE, UL508A, SEMI S2, etc.



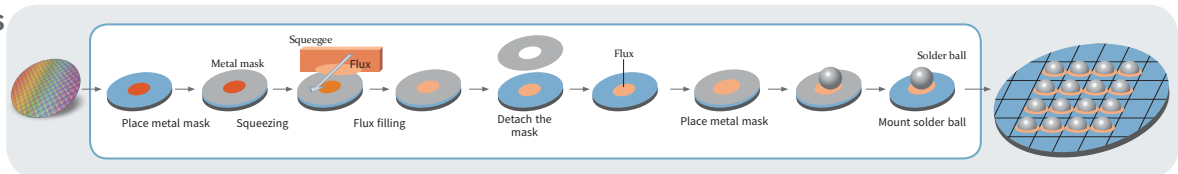
PRODUCT LINEUP 3

Wafer & Panel Level Ball Drop System (Ø40 µm)

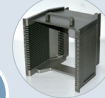
wBPS-DR1

• **Application** : WLCSP, Fan-Out PKG (FO-WLP, FO-PLP, FO-PoP)

• **Process**



Carrier : Cassette



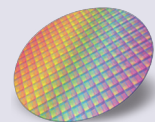
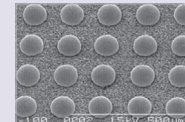
INPUT

Material : Wafer, Solder Ball



Interface Type : Downstream Link, Standalone

OUTPUT

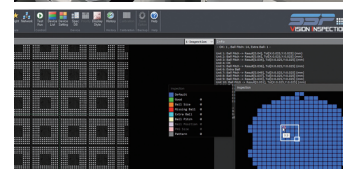
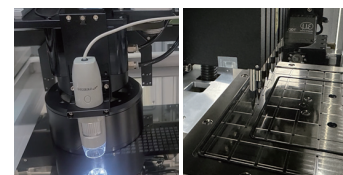


• **System Performance**

Application	WLCSP, Fan-Out PKG (FO-WLP, FO-PLP, FO-PoP)
Handling Capability	300 mm × 300 mm Panel, 8", 12" Wafer
Cycle Time / UPH	30 PPH (300 mm × 300 mm Panel)
Yield	99.9% (Ball Yield)
Placement Accuracy	± 0.02 mm
Min. Solder Ball Diameter	Ø0.04 mm
Min. Pitch	0.08 mm
Rework	Rework Module Included
Foot Print	6,380(L) × 1,780(W) × 1,910(H)

• **Optional Features**

- Auto Ball Supply
- Cleanliness : Class 1,000
- Certification : CE, UL508A, SEMI S2, etc.



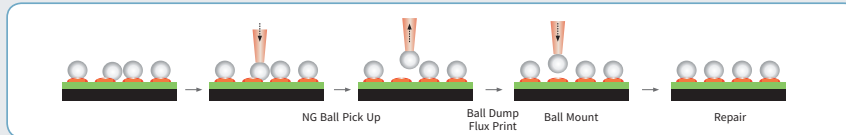
PRODUCT LINEUP 4

Reballing System (Ball Re-Do)

SBP-11 BRS

• **Application** : Ball Rework (BGA, WLCSP)

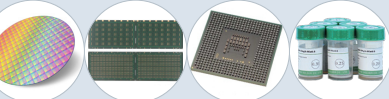
• **Process**



Carrier : Magazine, Boat

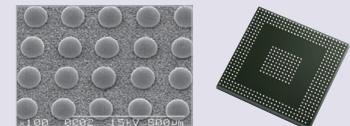
INPUT

Material : Wafer, Singulated Unit, Strip, Solder Ball



Interface Type : Downstream Link, Standalone

OUTPUT

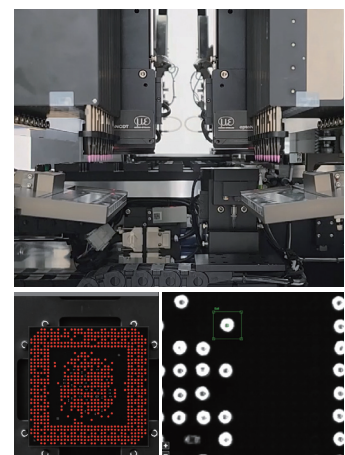


• **System Performance**

Cycle Time / UPH	Single Ball Only 14,000 ea < 25 sec (3×5 Array) 5 sec / Ball (Removal & Re-Do)
Placement Accuracy	± 0.025 mm
Min. Solder Ball Diameter	0.04 mm
Handling Capability	Unit 10-130 mm × 10-130 mm
Min. Pitch	0.08 mm
Foot Print & Weight	1,570(L) × 2,100(W) × 2,060(H)

• **Optional Features**

- Auto Ball Supply
- Cleanliness : Class 1,000
- Certification : CE, UL508A, SEMI S2, etc.



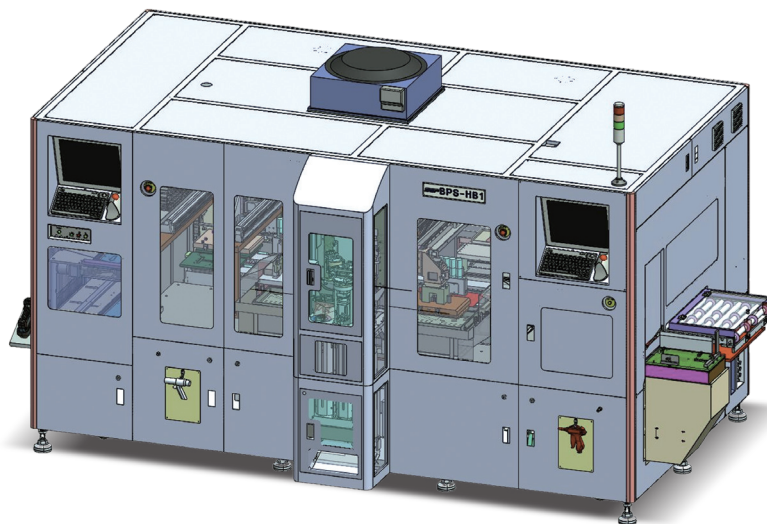
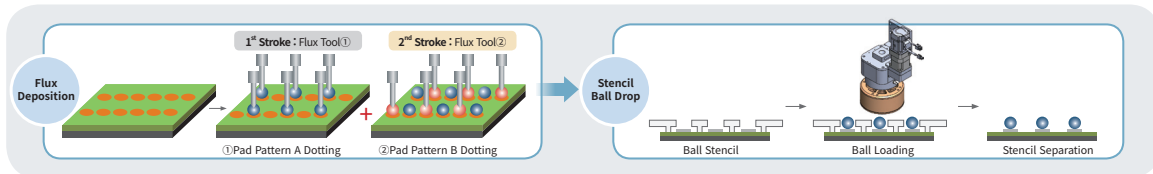
PRODUCT LINEUP 5

Micro Ball & Fine Pitch SBM (Ø40 µm)

BPS-Hybrid

• Application : FCCSP

• Process

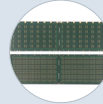


Carrier : Magazine



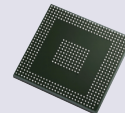
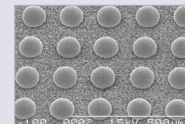
INPUT

Material : Strip, Solder Ball



Interface Type : Downstream Link, Standalone

OUTPUT

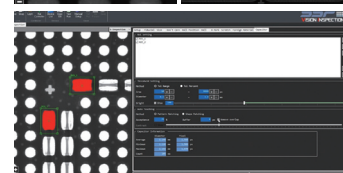
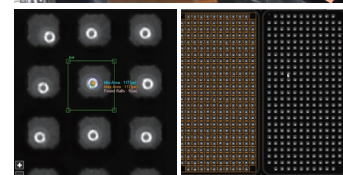


• System Performance

Cycle Time / UPH	45 sec
Yield	99.98%
Placement Accuracy	± 15 µm
Handling Capacity	Strip 50–95 mm (W) × 180–260 mm (L)
Min. Solder Ball Diameter	Ø40 µm
Min. Pitch	80 µm
Warpage Capability	Max. 10mm for Substrate
Rework	Additional Rework M/C is Required
Tooling Conversion Time	≤ 20 minutes

• Optional Features

- Auto Ball Supply
- Cleanliness : Class 1,000
- Certification : CE, UL508A, SEMI S2, etc.



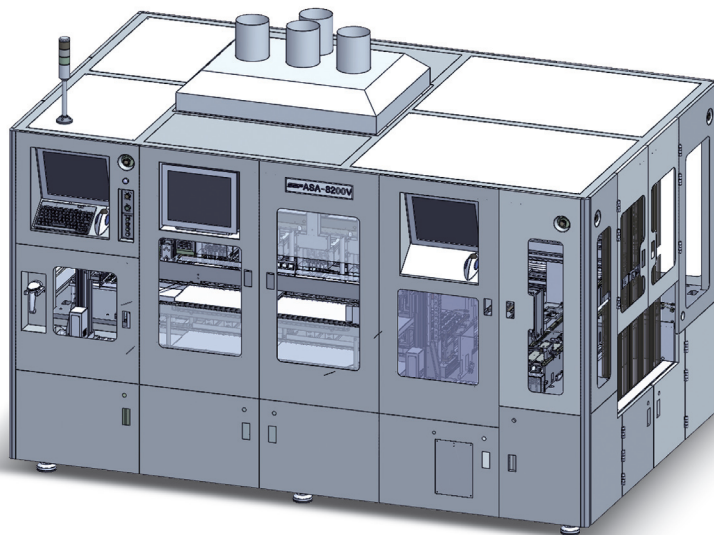
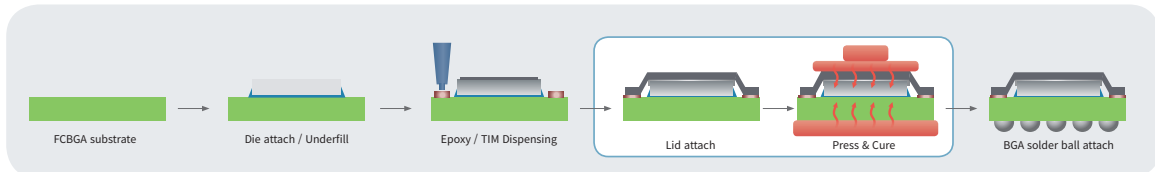
PRODUCT LINEUP 6

Lid Attach & Press Cure

ASA-8200V ASA-7200V

• **Application** : FCBGA, BGA, LGA

• **Process**



Carrier : Magazine, Boat



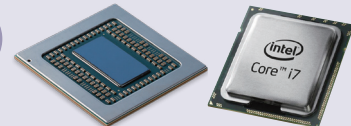
INPUT

Material : Lid/Heat Spreader, Unit



Interface Type : Standalone

OUTPUT

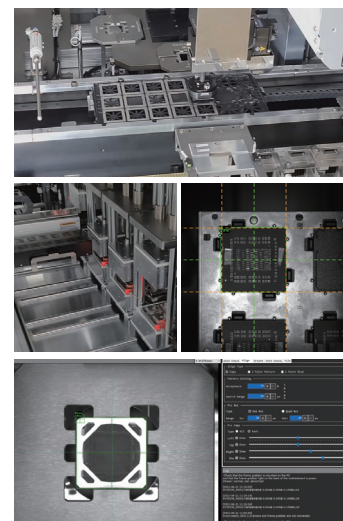


• **System Performance**

Handling Capability	ASA-7200V (Unit Max. 100 mm × 100 mm) ASA-8200V (Unit Max. 150 mm × 150 mm)
Cycle Time / UPH	1,000–1,300 UPH
Yield	99.98%
Attach Force Control	0.5–10 kgf (Real time monitoring)
Lid Attach Accuracy	± 0.03 mm, ±0.1 °
Press Force Control	± 10% (Max. 1,000 kgf)
Foot Print	3,750(L) × 2,000(W) × 2,300(H)

• **Optional Features**

- Cleanliness : Class 1,000
- Certification : CE, UL508A, SEMI S2, etc.
- Inspection Module : Epoxy Dispensing, Lid Offset, Lid Flatness
- Lid Plasma Module
- 4 × Press Cure : Parallel Processing



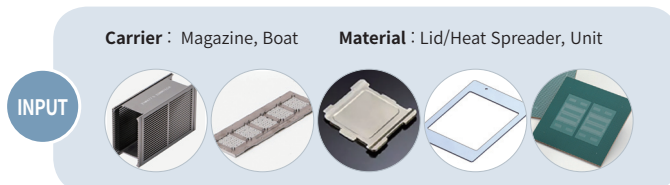
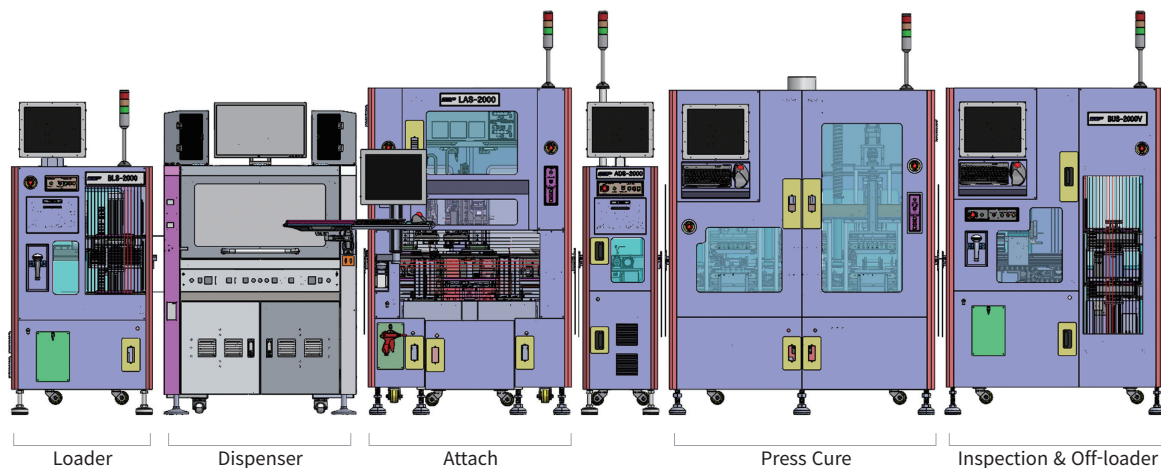
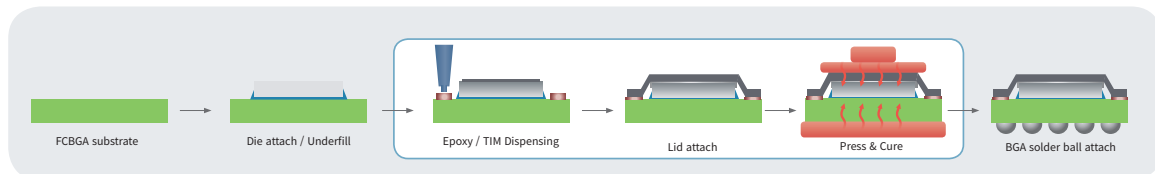
PRODUCT LINEUP 7

Lid Dispensing & Attach & Press Cure

DAP-423

• **Application** : FCBGA, BGA, LGA

• **Process**

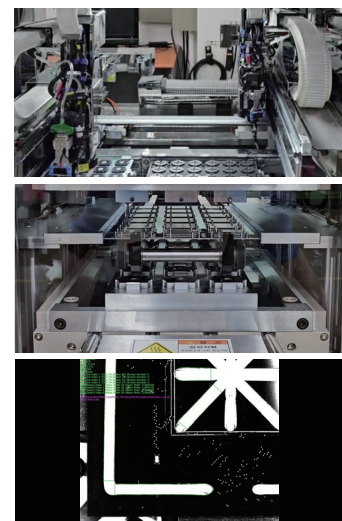


• **System Performance**

Handling Capability	Strip/Boat 62-210 mm (W) × 50-320 mm (L) Unit (Max.) 100 mm (W) × 100 mm (L)
Dispensing Area	330 × 210 mm Common area 110 mm
Cycle Time / UPH	Pick & Place 2.1 sec/Lid
Dispense Accuracy	±0.03 mm
Dispense Volume	Auto Calibration Function
Repeatability	10 mg ± 3 %, 5 mg ± 5 %, 1 mg ± 10 %
Attach Force Control	0.5-10 kgf (Real time monitoring)
Lid Attach Accuracy	± 0.03 mm, ±0.1 °
Press Force Control	± 10% (Max. 1,000 kgf)
Curing Temp. Capability	Tolerance ±5 °C, Max 220 °C
Nozzle Cleaning	3 Types (Suction, Clamping with Rubber, Stamping)
Foot Print	8,000(L) × 1,550(W) × 2,000(H)

• **Optional Features**

- Cleanliness : Class 1,000
- Certification : CE, UL508A, SEMI S2, etc.
- Inspection Module : Epoxy Dispensing, Lid Offset, Lid Flatness
- Lid Plasma Module
- 3 × Snap Cure : Parallel Processing



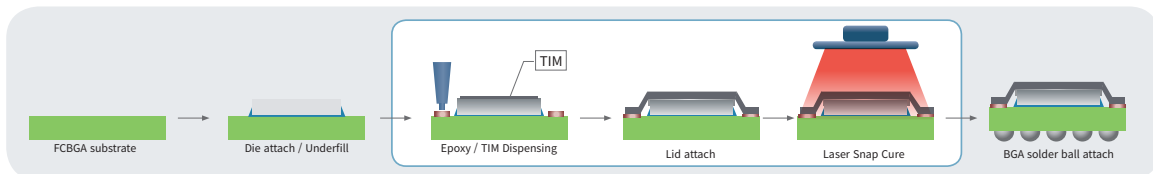
PRODUCT LINEUP 8

Metal TIM Attach & Laser Snap Cure

DAL-T1

• **Application** : FCBGA, BGA, LGA

• **Process**



Carrier : Magazine, Boat



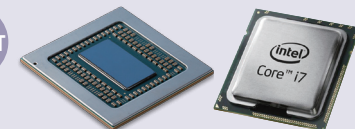
INPUT

Material : Lid, Unit



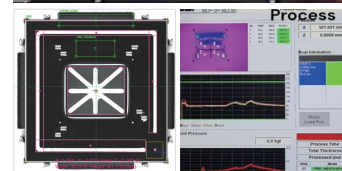
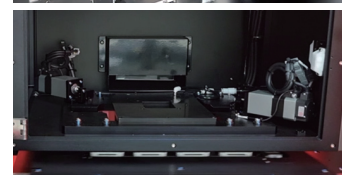
Interface Type : Standalone

OUTPUT



• **System Performance**

Handling Capability	Unit (Max.) 100 mm (W) × 100 mm (L) Boat (Max.) 160 mm (W) × 310 mm (L) TIM (Max.) 38 mm (W) × 38 mm (L) Lid (Max.) 100 mm (W) × 100 mm (L)
Cycle Time / UPH	P&P 7.5 sec/Lid
Accuracy	Dispenser $\pm 30 \mu\text{m}$ / TIM & Lid Attach $\pm 30 \mu\text{m}$
BLT Tolerance	$\pm 10 \mu\text{m}$
Dispense Volume	10 mg $\pm 3 \%$, 5 mg $\pm 5 \%$
Repeatability	
Laser Type	IR (4 kW, FOV 180×180 mm)
CompressionForce Control	0.5–500 kgf
Foot Print	2,400(L) × 1,500(W) × 1,910(H)



• **Optional Features**

- Cleanliness : Class 1,000
- Certification : CE, UL508A, SEMI S2, etc.

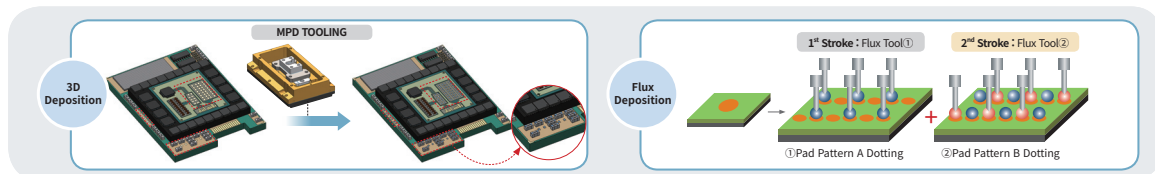
PRODUCT LINEUP 9

Paste Dotting System for SiP / 2.5D Packaging

MPD-S1

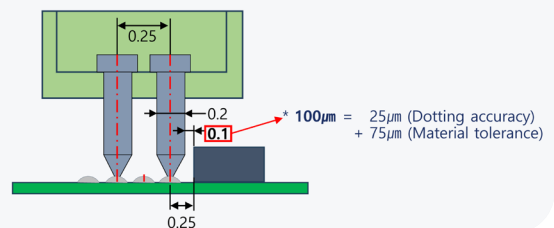
• **Application** : 2.5D, 3D Packaging, Micro LED

• **Process**



▪ Min pad Pitch

- Dual Tooling : 125 μm
- Min gap between Pin and Device to prevent interference

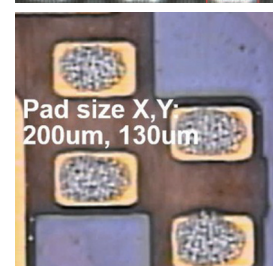
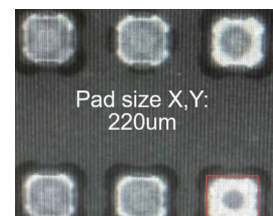


▪ Min. Dotting Size Diameter : $\varnothing 70 \mu\text{m}$



• System Performance

Handling Capability	Strip 62-135 mm (W) × 50-280 mm (L)
Cycle Time / UPH	30,000 Dots in 12-15 sec
Deposition Accuracy	± 25 μm
Min. Deposition Diameter	$\varnothing 60 \mu\text{m}$ (for 01005 Capacitor Available)
Min. Deposition Pitch	125 μm
Min. Pad edge to Component Distance	100 μm
Paste Volume Tolerance	± 10 %
Warp Capability	Max. 600 μm for Substrate
Individual Pin Force Control	Max. 3gf per Pin
Auto Pin Tool Cleaning	DI Water / IPA (≤ 1 min)
Tooling Conversion Time	≤ 20 minutes
Foot Print	1450(L) × 1,200(W) × 2,070(H)



• Optional Features

- Cleanliness : Class 1,000
- Certification : CE, UL508A, SEMI S2, etc.

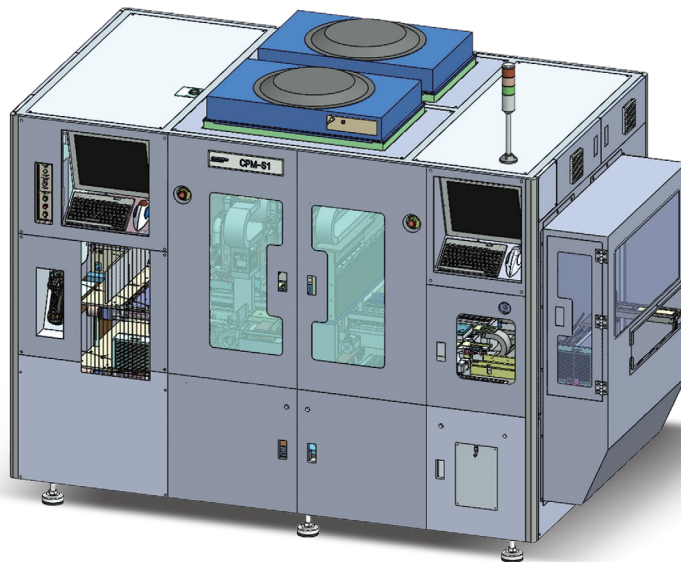
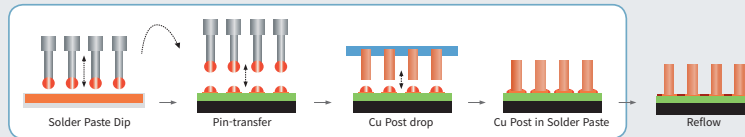
PRODUCT LINEUP 10

Copper Post Mounting

CPM-S1

• **Application** : Cu Post Mounting

• **Process**



Carrier : Magazine, Boat

INPUT

Material : Strip, Singulated Unit, Solder Paste

Interface Type : Up/Downstream Link, Standalone

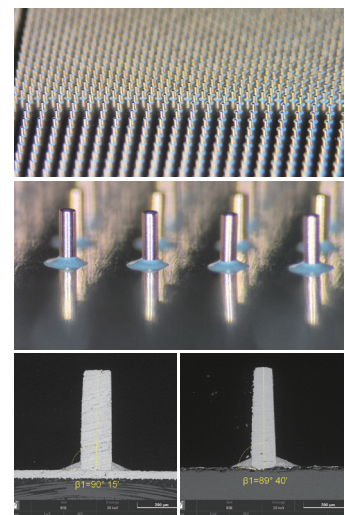
OUTPUT

• **System Performance**

Handling Capability	Strip 62~135 mm (W) × 50~280 mm (L), Unit, Wafer Available
Cu Post Position Accuracy	±25 μm
Min. Diameter of Cu Post	Ø120 μm
Aspect Ratio of Cu Post	≤ 5.0
Min. Pitch of Cu Post	250 μm
Cu Post Tilt Angle	< 15 °
IMC Joint Strength	3 MPa
IMC Thickness (BLT)	5~25 μm
Warpage Capability	Max. 600 μm for Substrate
Tooling Conversion Time	≤ 20 minutes

• **Optional Features**

- Auto Copper Post Supply
- Cleanliness : Class 1,000
- Certification : CE, UL508A, SEMI S2, etc.



PRODUCT LINEUP 11

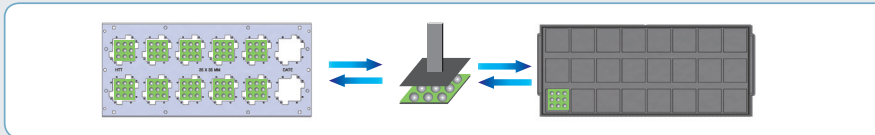
Pick & Place System (Boat-to-Tray & Tray-to-Boat)

APP-8000L

APP-8000URV

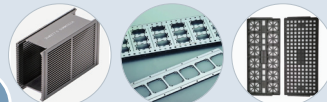
• Application : FCBGA, BGA

• Process



Carrier : Magazine, Boat, Tray

INPUT



Material : Lid, Unit



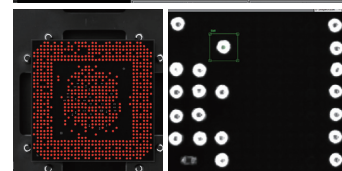
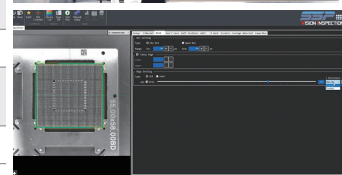
Interface Type : Upstream Link, Standalone

OUTPUT



• System Performance

Handling Capability	Unit 15-150 mm (W) × 15-150 mm (L) Boat 130-210 mm (W) × 250-310 mm (L)
Cycle Time / UPH	Without QC Inspection 6,000 UPH (4 × 10 Boat Array) With QC Inspection 5,000 UPH (4 × 10 Boat Array, All Good Unit)
Yield	99.98%
Placement Accuracy	± 0.05mm
Quick Conversion Time	≤ 10 minutes (Transfer Table, Unit Picker Pad)
Foot Print	2,820(L) × 1,740(W) × 1,600(H)



• Optional Features

- Cleanliness : Class 1,000
- Certification : CE, UL508A, SEMI S2, etc.

PRODUCT LINEUP 12

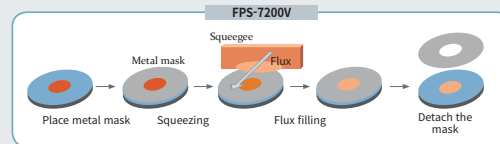
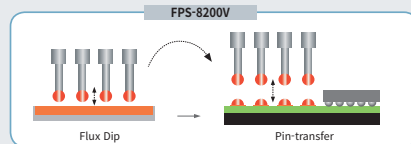
Flux Printing System (Dotting, Stencil)

FPS-8200V

FPS-7200V

• **Application** : FCBGA, BGA, LGA

• **Process**



Carrier : Magazine, Boat

INPUT

Material : Strip, Singulated Unit

Interface Type : Downstream Link, Standalone

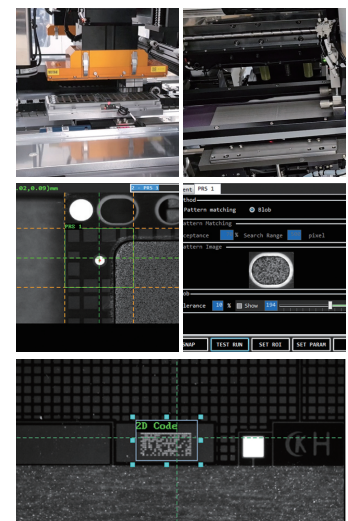
OUTPUT

• **System Performance**

Cycle Time	7 sec/strip
Pre-screen printing Method	Printing Flux on the strip
Printing Flux on the strip	62mm – 95mm Strip
Quick Conversion Time	Vacuum Block, Flux Stencil
Foot Print	2,250 mm(L) × 1,250 mm(W) × 1,720 mm(H)
Foot Weight	2,000 kg
Foot Print	3,750(L) × 2,000(W) × 2,300(H)

• **Optional Features**

- Cleanliness : Class 1,000
- Certification : CE, UL508A, SEMI S2, etc.



PRODUCT LINEUP 13

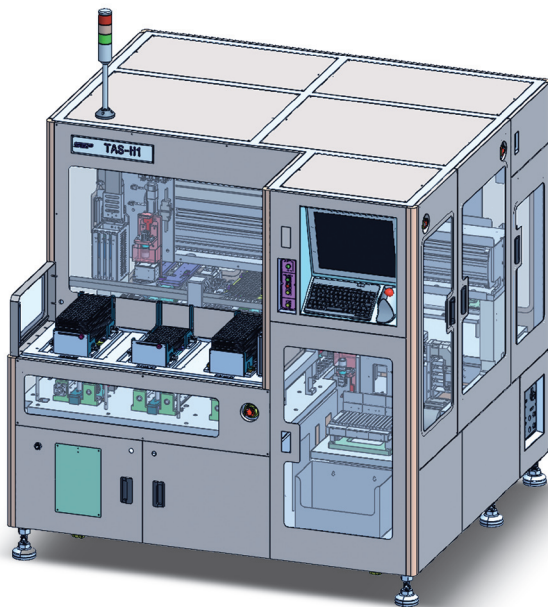
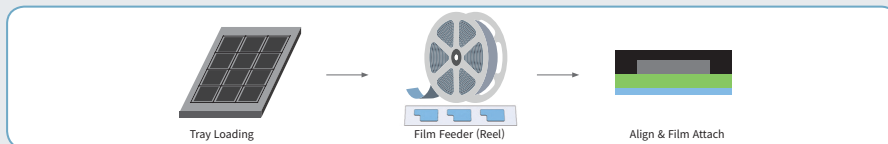
Tape Attach System

TAS-H1

TAS-2000

• **Application** : Test, Packing

• **Process**



Carrier : Magazine, Tray, Reel

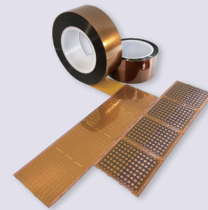
INPUT

Material : Strip, Tape, EMI Shield Tape



Interface Type : Standalone

OUTPUT

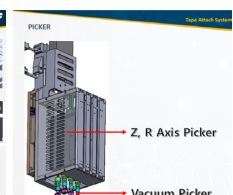
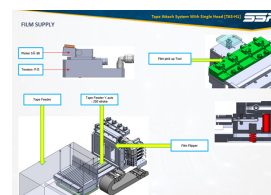


• **System Performance**

Application	Attaching Protection Film
Handling Capability	Film Width 10-24 mm (4 × Tape Feeders)
Cycle Time / UPH	400 Units / Hour
Attach Accuracy	± 0.03 mm
Footprint	1,790(L) × 1,650(W) × 1,750(H)

• **Optional Features**

- Cleanliness : Class 1,000
- Certification : CE, UL508A, SEMI S2, etc.



PRODUCT LINEUP 14

Tape Detaching System

TDS-1000

TDS-2000

• **Application** : Tape Delamination

• **Process**



Carrier : Magazine, Boat

INPUT

Material : Strip, Singulated Unit

Interface Type : Downstream Link, Standalone

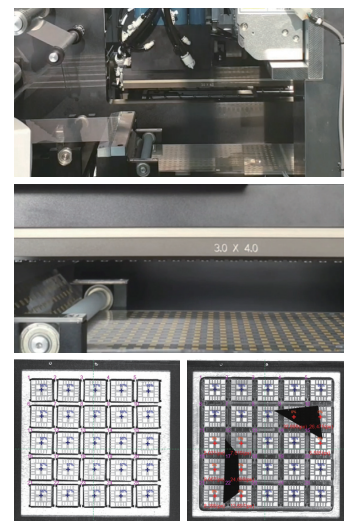
OUTPUT

• **System Performance**

Application	Detaching Tape
Handling Capability	Unit 3-20 mm (W) × 3-20 mm (L) Strip 60-100 mm (W) × 200-300 mm (L)
Cycle Time / UPH	55 Trays / Hour
Yield	99.98%
Placement Accuracy	± 0.15 mm
Footprint	1,825(L) × 1,615(W) × 1,675(H)

• **Optional Features**

- Cleanliness : Class 1,000
- Certification : CE, UL508A, SEMI S2, etc.



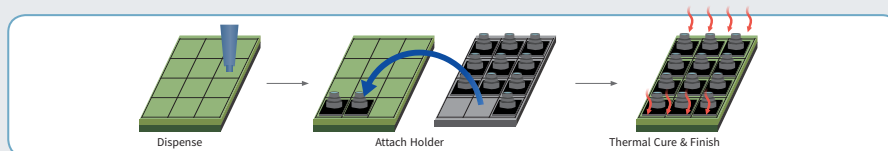
PRODUCT LINEUP 15

Dispensing & Camera Module Attach & Snap Cure System

DAS-6230 DAS-6230S

• **Application** : Camera Module, Holder Attach

• **Process**

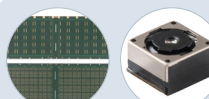


Carrier : Magazine, Tray



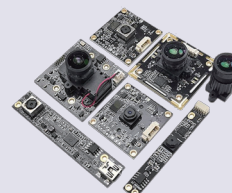
INPUT

Material : Strip, Camera Housing



Interface Type : Standalone

OUTPUT

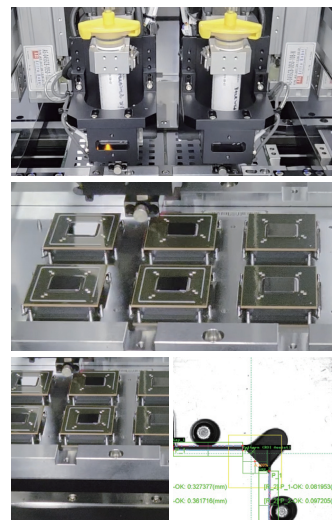


• **System Performance**

UPH	1,750–1,850 units with BOSS PIN 1,400 units Without BOSS PIN
Yield Performance	99.99%
Placement Accuracy	± 0.015 mm for Lens PRS ± 0.030 mm for Holder PRS
Handling System	Strip & Tray Handling
Inspection System	4-PRS Camera System Laser Height Prober System : ±5 μm
Application Package	62–95 mm(W) × 180–250 mm(L)
Product Flexibility	All kinds of Camera Module can be applied
Foot Print	2,300(L) × 1,400(W) × 1,800(H)
Foot Weight	2,500 kg

• **Optional Features**

- Cleanliness : Class 1,000
- Certification : CE, UL508A, SEMI S2, etc.



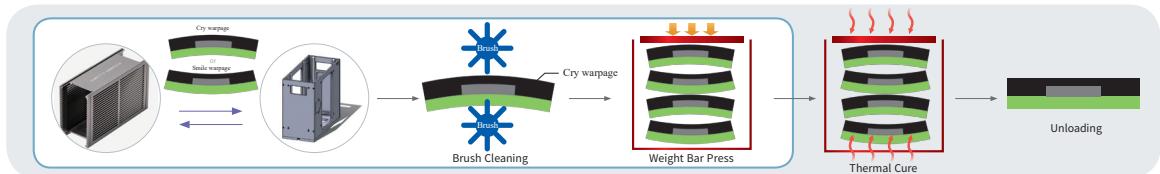
PRODUCT LINEUP 16

Weight Bar Handling System with Brush Cleaning

MCS-P2

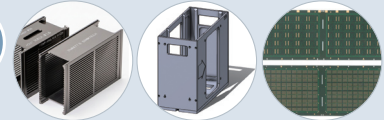
• **Application** : Post Mold Cure

• **Process**



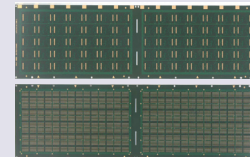
Carrier : Magazine **Material** : Strip

INPUT



Interface Type : Standalone

OUTPUT

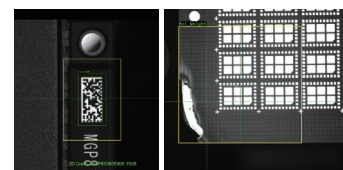
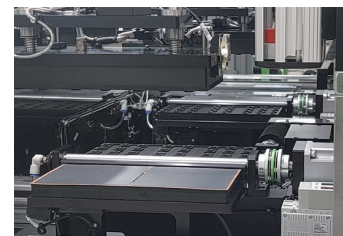


• **System Performance**

Handling Capability	Strip 74-95 mm (W) × 50-240 mm (L) Strip Magazine, Strip Stack Magazine
Cycle Time / UPH	200 Strips/Hour
Substrate Cleaning	Brush with Vacuum
Warpage Capability	Max. 10 mm for Substrate
Foot Print	1,820(L) × 1,850(W) × 1,861(H)

• **Optional Features**

- Cleanliness : Class 1,000
- Certification : CE, UL508A, SEMI S2, etc.
- Brush Cleaning only Mode



PRODUCT LINEUP 17

SMT Module Automation System

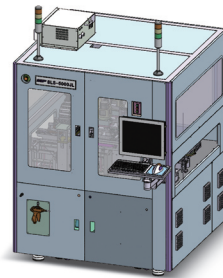
SSP Strip Loader



SLS-5000L

Cycle Time / UPH : 490 Strips / Hour
Option : 2DID Inspection
Footprint : 1,350(L) × 1,100(W) × 1,860(H)

SSP Jig & Cover Loader



BLS-5000JL

Cycle Time / UPH : 350~400 Strips / Hour
Option : 2DID Inspection
Footprint : 1,400(L) × 1,400(W) × 1,760(H)

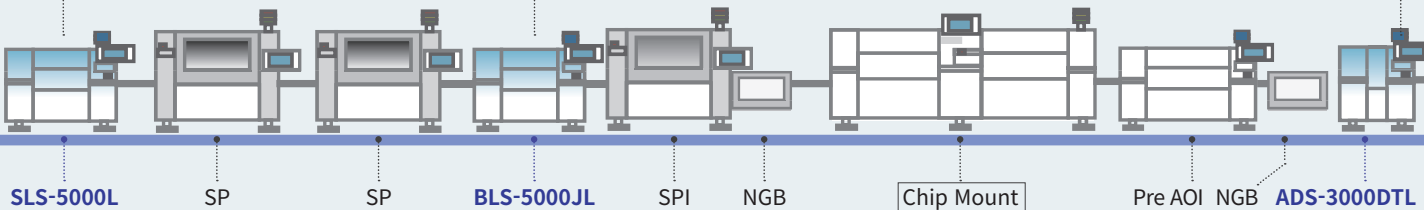
SSP Divertor(1⇔2)



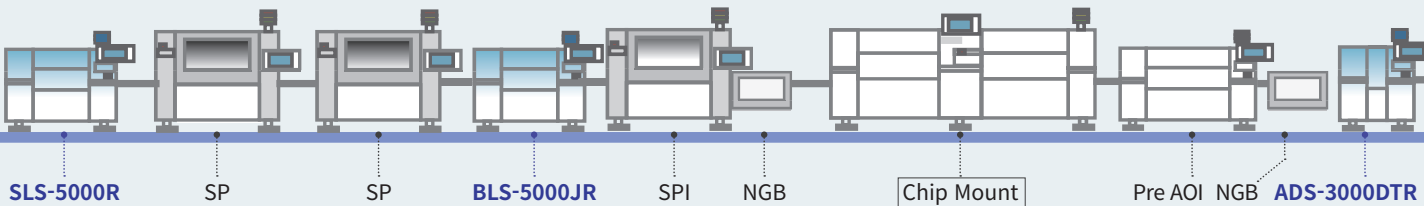
ADS-3000DTL

Cycle Time / UPH : 400 Strips / Hour
Footprint : 1,500(L) × 650(W) × 1,550(H)

W/T



W/T



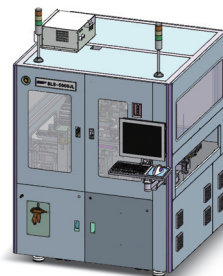
SSP Strip Loader



SLS-5000R

Cycle Time / UPH : 490 Strips / Hour
Option : 2DID Inspection
Footprint : 1,350(L) × 1,100(W) × 1,860(H)

SSP Jig & Cover Loader



BLS-5000JR

Cycle Time / UPH : 350~400 Strips / Hour
Option : 2DID Inspection
Footprint : 1,400(L) × 1,400(W) × 1,760(H)

SSP Divertor(1⇔2)



ADS-3000DTR

Cycle Time / UPH : 400 Strips / Hour
Footprint : 1,500(L) × 650(W) × 1,550(H)

REALIZING TECHNOLOGY FOR MAKING IMAGINATION INTO REALITY

SSP Collator & Buffer(2⇌3)



RCS-3000CTL

Cycle Time / UPH : 400 Strips / Hour
Footprint : 2,000(L) × 850(W) × 1,700(H)

SSP Collator & Buffer(3⇌1)



ACS-3000DCT

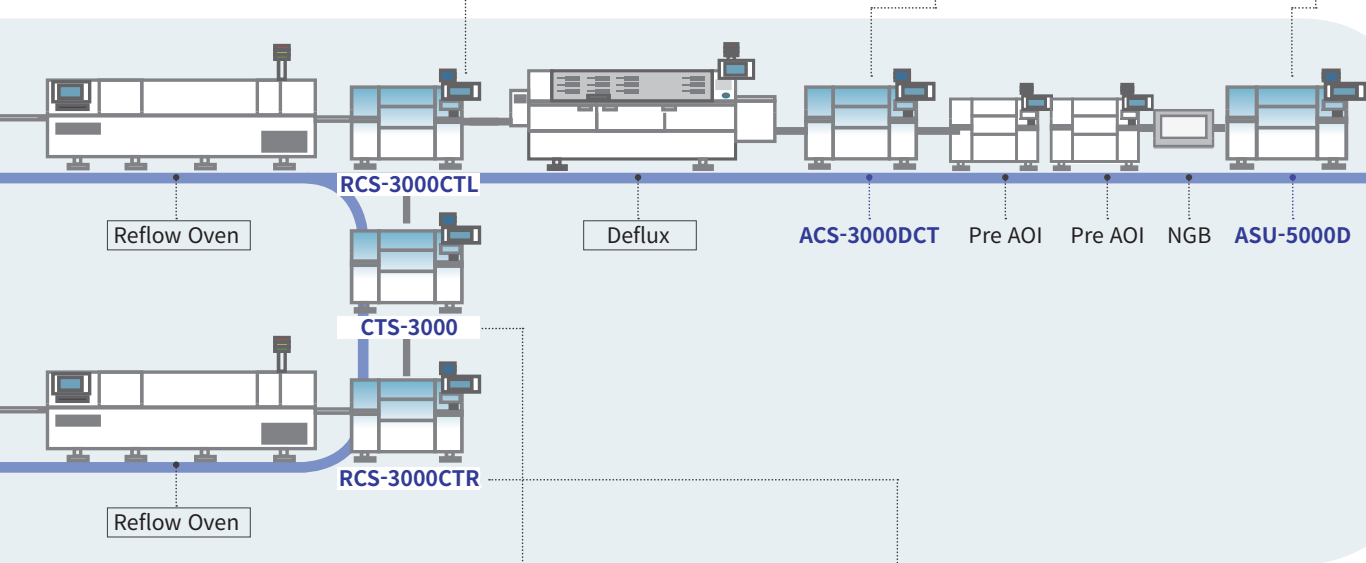
Cycle Time / UPH : 400 Strips / Hour
Footprint : 1,800(L) × 850(W) × 1,700(H)

SSP Jig, Cover, Strip Unloader (4Port)



ASU-5000D

Cycle Time / UPH : 400 Strips / Hour
Footprint : 2,640(L) × 2,100(W) × 1,700(H)

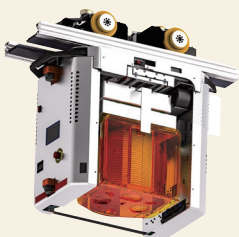


Handling Capability

Strip : 50-95 mm (W) × 185-250 mm (L)
Boat : 130-210mm (W) × 250-310mm (L)

* Common Specifications

OHT Available



SSP Bridge



CTS-3000

Cycle Time / UPH : 400 Strips / Hour
Footprint : 1,150(L) × 550(W) × 1,010(H)

SSP Buffer



RCS-3000CTR

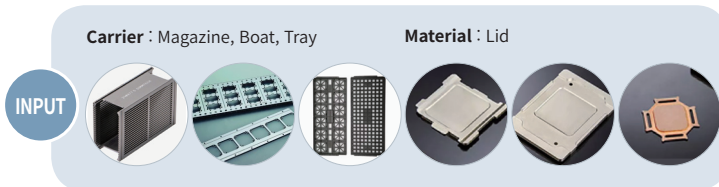
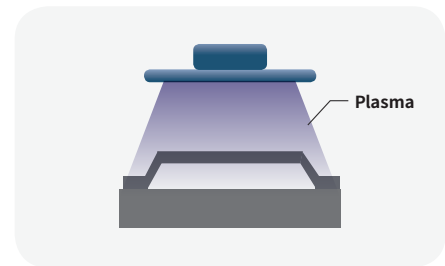
Cycle Time / UPH : 400 Strips / Hour
Footprint : 2,000(L) × 850(W) × 1,700(H)

PRODUCT LINEUP 18

Lid Plasma Cleaning System

LCS-PV

- **Application** : Lid Plasma Cleaning, Lid Laser Marking

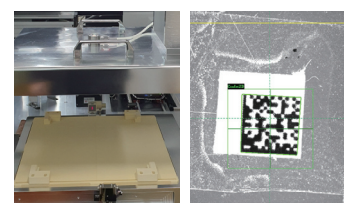
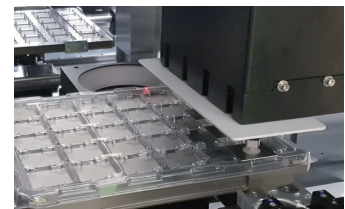


• System Performance

Handling Capability	Lid (Max.) 100 mm(W) × 100 mm(L) Boat 130–210 mm(W) × 250–320 mm(L)
Lid Loading	Lid Magazine Loader
Lid Pick & Place	4 × Vacuum Picker
Cycle Time / UPH	Pick & Place 2.1 sec/Lid
Marking	Lid 2DID Marking
Foot Print	3,250(L) × 2,150(W) × 1,890(H)

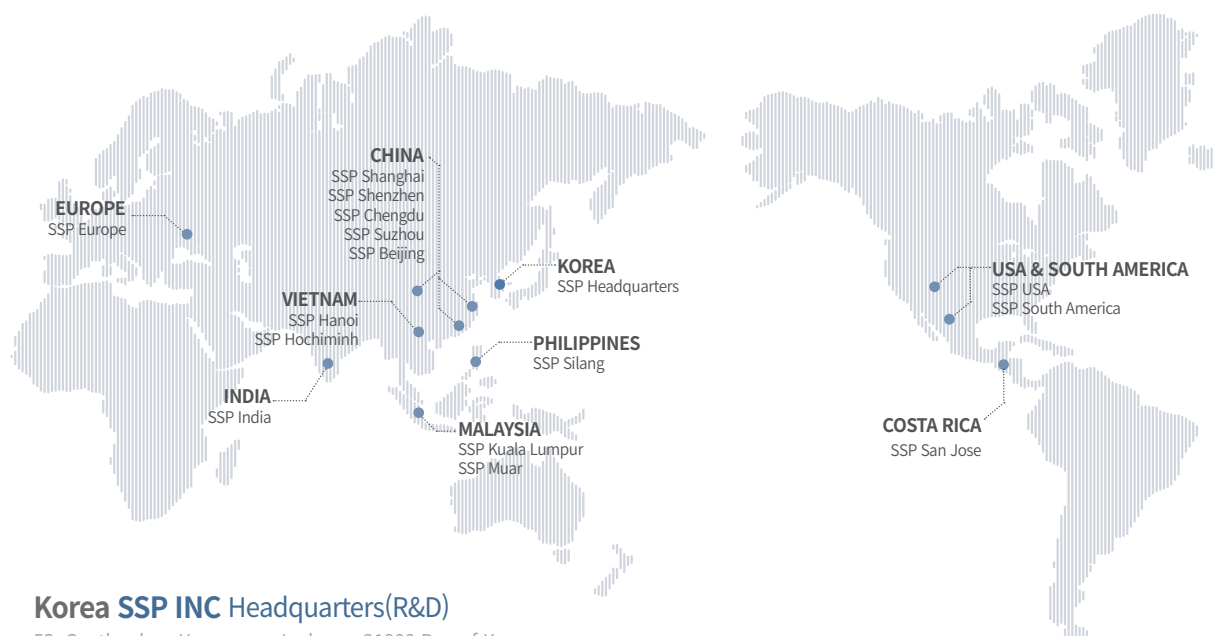
• Optional Features

- Cleanliness : Class 1,000
- Certification : CE, UL508A, SEMI S2, etc.



Global Network

SSP's global network spreading worldwide



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Taiwan

China

Malaysia

Thailand

India



01

Quality

Realizing technology for
making imagination into reality

02

Environment

Quality, Environment Safety & Health

SSP enacts and executes QESH management policy as follows to accomplish customer satisfaction through stable supply of best quality equipment, pursue eco-friendly management, prevent accident and improve health and for employees.

03

Safety & Health

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